

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	207	HAN-CHERNG-CHYI.in. or CHEN-MAO-MIN.in. or WANG-PO-KANG.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/20 06:32
L2	731	planariz\$5 with (photoresist or insulat\$3) with coil	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/20 06:43
L3	9	1 and 2	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/20 06:33
L4	0	("2005/0180049").URPN.	USPAT	OR	ON	2006/01/20 06:43
L5	0	planariz\$5 near alumina near coil	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/20 06:43
L6	5	(planariz\$5 near alumina) with coil	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/20 06:44
S2	3694	451/5,41.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/08/31 09:07
S3	5325	427/127,128.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/08/30 13:33
S4	6931	360/121-126,317.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/08/30 13:33
S5	5215	29/592.1,603.12-603.16,603.18,829, 831,851,885.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:30
S6	1	(substrate or wafer) near (trench\$2 or cavit\$3) near coil	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:14
S7	802	(trench\$2 or cavit\$3) near coil	USPAT; JPO; DERWENT	OR	ON	2005/08/30 13:39
S9	894	etch\$3 near (substrate or wafer) near (trench\$2 or cavit\$3)	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:12
S10	0	S7 and S9	USPAT; JPO; DERWENT	OR	ON	2005/08/30 13:39

S11	98	(trench\$2 or cavit\$3) near (form\$3 or embedd\$3) near coil	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:28
S12	1	S5 and S11	USPAT; JPO; DERWENT	OR	ON	2005/08/30 13:40
S13	26	("4102683"   "4652954"   "4684438"   "5034089"   "5045417"   "5126220"   "5153083"   "5414580"   "5448822"   "5515221"   "5566442"   "5621592"   "5649351"   "5658470"   "5665251"   "5666249"   "5681426"   "5695656"   "5700380"   "5729887"   "5742458"   "5779923"   "5894388"   "6226149"   "6304414"   "6515826").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/30 13:40
S14	4	(trench\$2 or cavit\$3) near (embedd\$3) near coil	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:02
S15	116	HAN-CHERNG-CHYI.in. or CHEN-MAO-MIN.in. or WANG-PO-KANG.in.	USPAT; JPO; DERWENT	OR	ON	2006/01/20 06:32
S16	0	S9 and S15	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:03
S17	2	S7 and S15	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:03
S18	5	("6304414"   "6317280"   "6325947"   "6333830"   "6339523").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/30 14:06
S19	11	((("6317288") or ("6466404") or ("6396660") or ("6339523") or ("6466401"))).PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2005/08/30 14:07
S20	10	S11 and planariz\$3	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:09
S21	0	etch\$3 near (substrate or wafer) near (trench\$2 or cavit\$3) near coil	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:12
S22	205	(substrate or wafer) with (trench\$2 or cavit\$3) with coil	USPAT; JPO; DERWENT	OR	ON	2005/08/30 14:14
S23	16	(substrate or wafer) with (trench\$2 or cavit\$3) with coil	EPO; JPO	OR	ON	2005/08/30 14:15
S24	0	((trench\$2 or cavit\$3) near (form\$3 or embedd\$3) near coil) with planariz\$4	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:29

S25	6931	360/121-126,317.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:29
S26	6931	S25 or S25	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:29
S27	5215	29/592.1,603.12-603.16,603.18,829, 831,851,885.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:30
S28	419	S25 and S27	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:30
S29	11727	S25 or S27	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:30
S30	8	photoresist with deposit\$3 with coil with planariz\$5	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:31
S31	7	S30 and @ad<"20030825"	USPAT; JPO; DERWENT	OR	ON	2005/08/30 15:31
S32	471	(spin adj coating) near (photoresist)	USPAT; JPO; DERWENT	OR	ON	2005/08/31 09:07
S33	0	(spin adj coating) near (photoresist) near coil	USPAT; JPO; DERWENT	OR	ON	2005/08/31 09:07
S34	2	(spin adj coating) near (photoresist) with coil	USPAT; JPO; DERWENT	OR	ON	2005/08/31 09:07